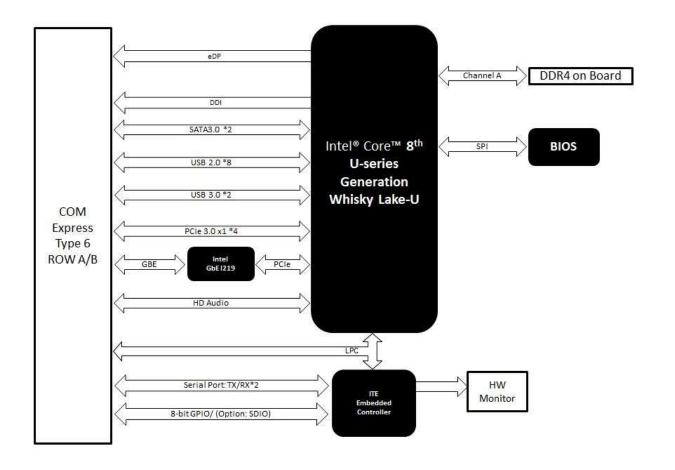


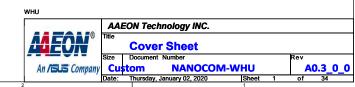
**Project Name: NANOCOM-WHU** 

Project Number: Version: A0.3\_0\_0

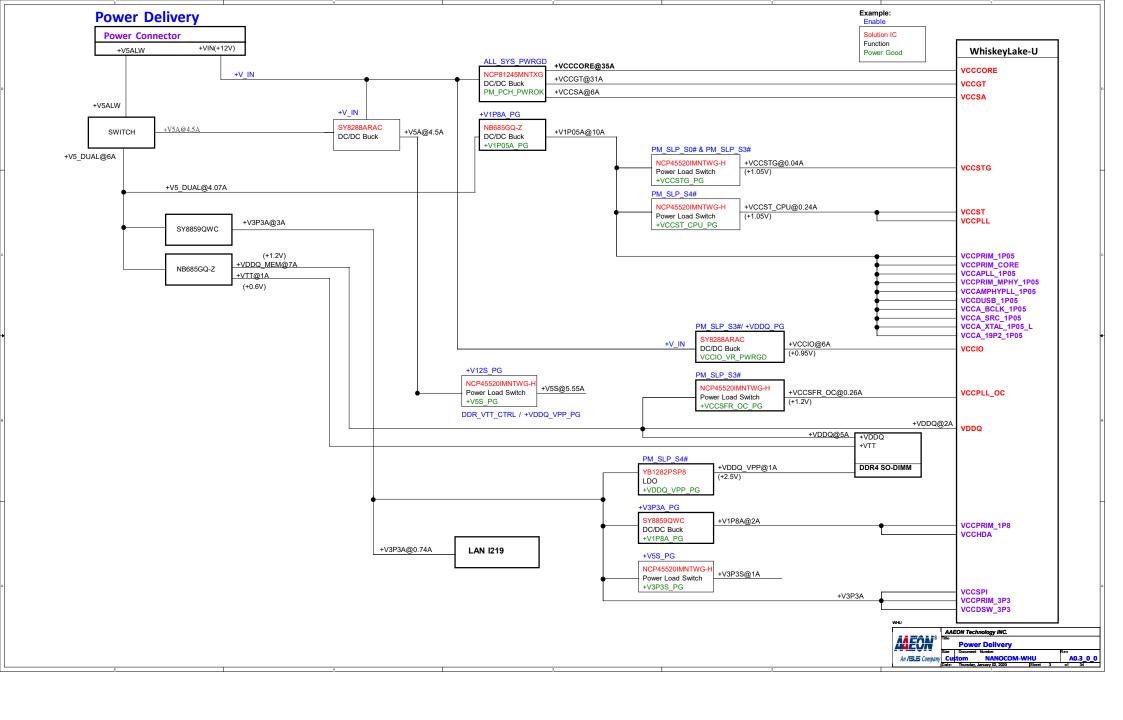
# System block diagram

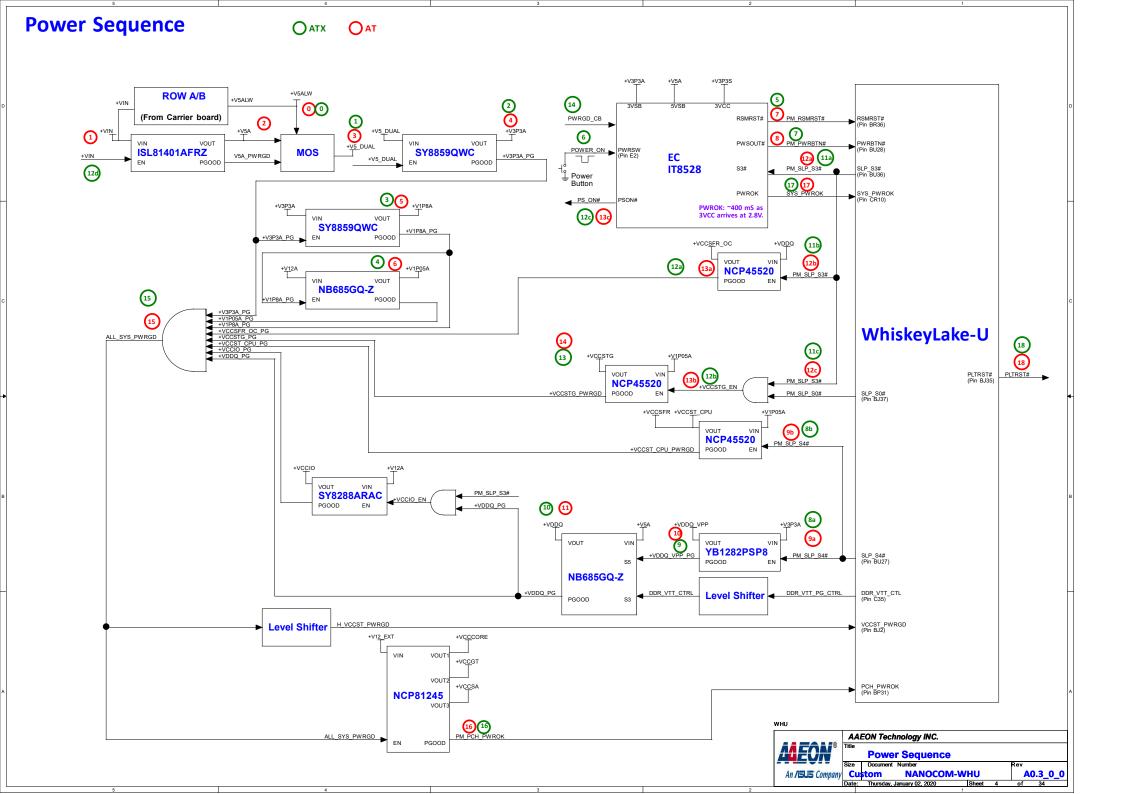


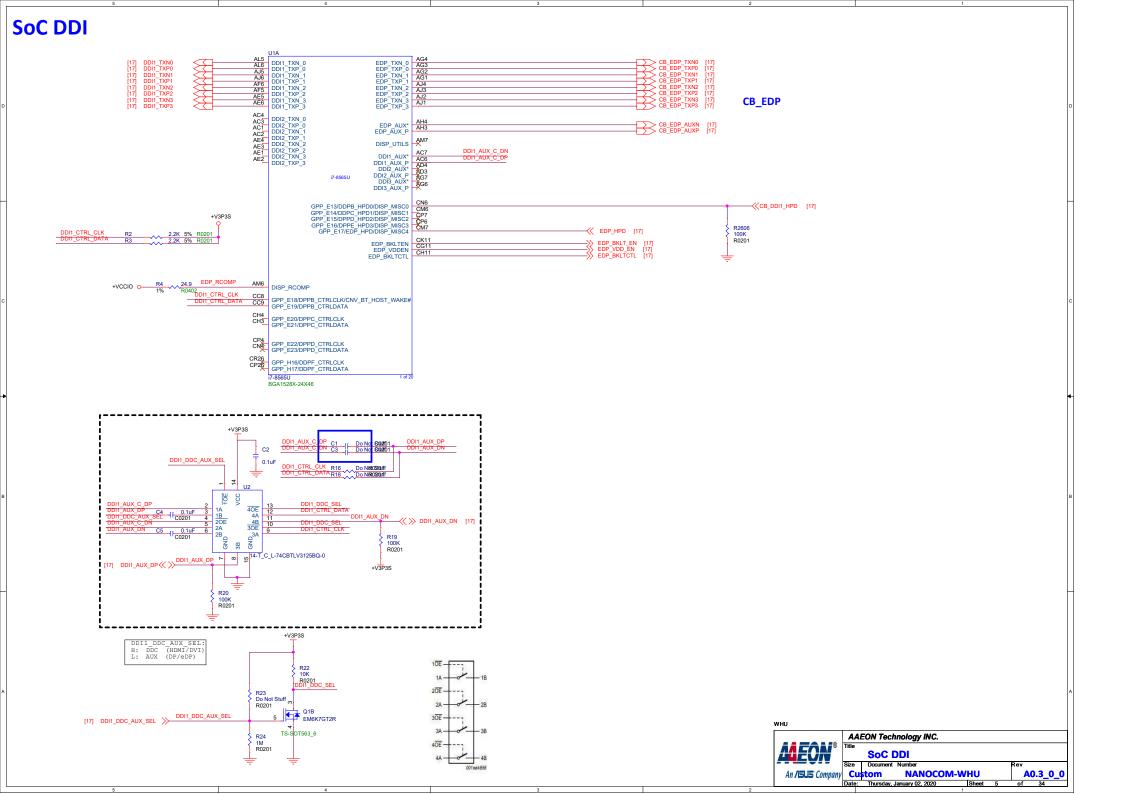
Page	Index
1	Cover Sheet
2	System Setting
3	Power Delivery
4	Power Sequence
5	SoC DDI
6	SoC DDR4
7	SoC SPI/LPC/SMBus
8	SoC HDA/SD
9	SoC PCIe/SATA/USB
10	SoC PCIE_CLK/ RTC
11	SoC eMMC
12	SoC System
13	SoC Power
14	PCH Power
15	SoC GND
16	SoC Strap
17	TYPE10 RAW A/B
18	DDR4
19	DDR4
20	LAN-1219
21	EC-IT8528
22	RSMEST# Control
23	FAN/BIOS/ LPC/ HW Monitor
24	NV5A Dual_ Discharge_Misc
25	PWR_+V5A/ +V3P3A
26	PWR_+V1P05A/ +VCCIO
27	PWR_+VDDQ/+VDDQ_VPP/+V1P8A
28	PWR_+VCCSTG/+VCCSFR_OC
29	PWR +V12S/ +V5S/ +V3P3S
30	PWR_IMVP8 Controller
31	PWR_+VCCCORE
32	PWR_+VCCGT/ +VCCSA
33	Revision History
34	
35	
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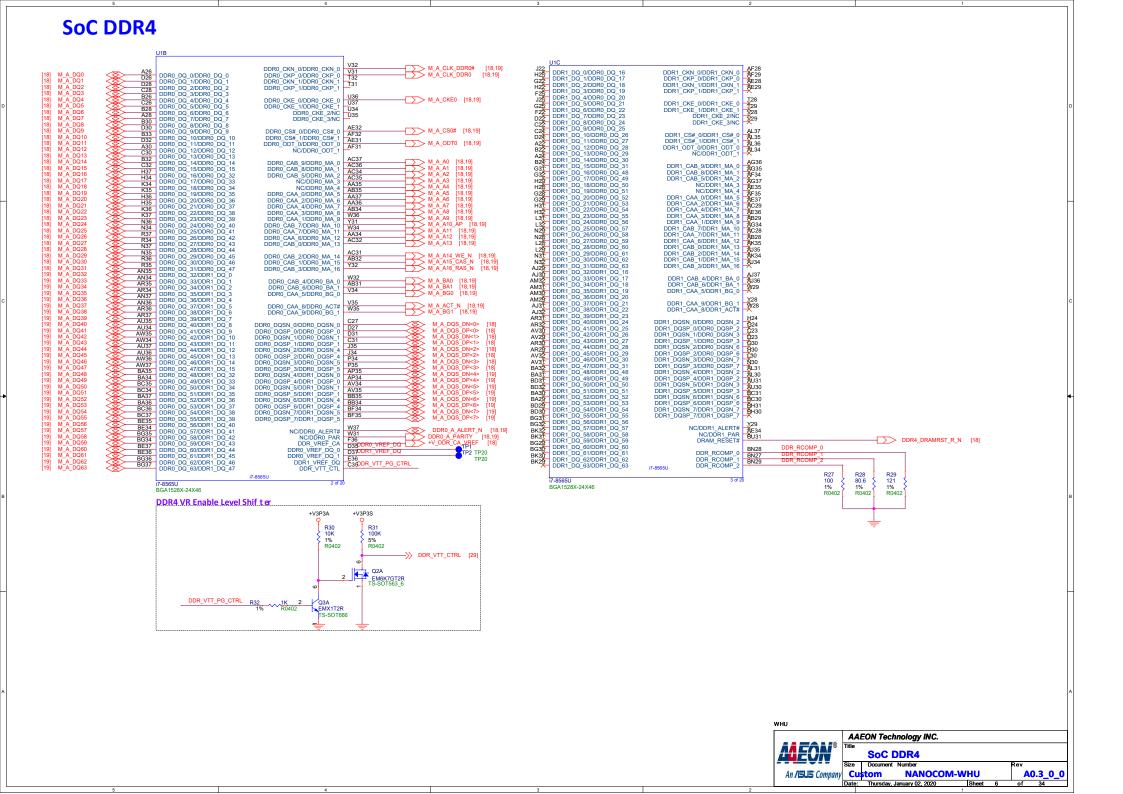


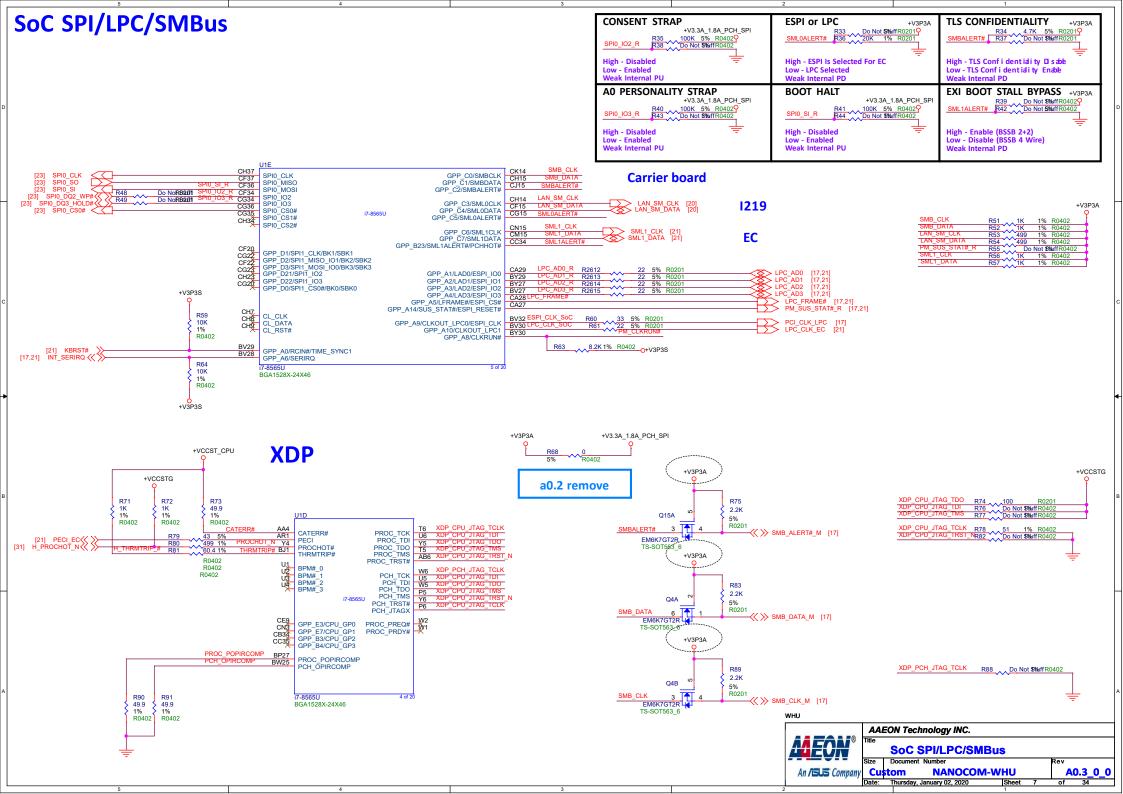
#### **SoC GPIO Pins: EC GPIO Pins:** Power Well Default GPIO Function Location GPP G0/SD CMD +V3P3A GPP G1/SD DATA0 +V3P3A GPP G2/SD DATA1 +V3P3A GPP G3/SD DATA2 +V3P3A GPP G4/SD DATA3 +V3P3A GPI0 GPI1 GPI2 GPI3 GPO0 GPO1 GPO2 GPO3 SMI# SCI# GPP G4/SD DATA: GPP G5/SD CD# GPP G6/SD CLK GPP G7/SD WP GPP C22 GPP C23 +V3P3A +V3P3A SMBus/I2C Addresses: **Board ID** Device address 0XC8 ID0 ID1 Description Micron DDR4 8G Samsung DDR4 4G N/A N/A **PCB Footprints** вом Description MOSFET BJT 9697NAWU06-D eleron 4305UE.DDR4 4GB(Samsung).eMMC 32G 9697NAWU07-D I3-8145UE.DDR4 8GB(Micron).eMMC 64G 9697NAWU08-D I5-8365UE.DDR4 8GB.(Micron).eMMC 64G 9697NAWU09-D I7-8665UE.DDR4 8GB(Micron).eMMC 64G PCB STACK: Board: FR4 Impedence: 50ohm +/-10% Thickness: 2.0mm +-10% ☐ Layer 1 : Component (Top) Layer 2 : GND (GND1) Layer 3 : Signal (IN1) Layer 4 : GND (GND2) Layer 5 : Signal (IN2) Layer 6 : POWER (VCC) Layer 7 : POWER (VCC) Layer 8 : Signal (IN3) Layer 9 : GND (GND3) ☐ Layer 10 : Signal (IN4) Layer 11 : GND (GND4) Layer 12 : Signal (IN5) WHU AAEON Technology INC. Layer 13 : GND (GND5) **MEON®** ☐ Layer 14 : Solder (Bottom) **System Setting** A0.3\_0\_0 of 34 Custom NANOCOM-WHU An /ISUS Company Date: Thursday, January 02, 2020 Sheet 2

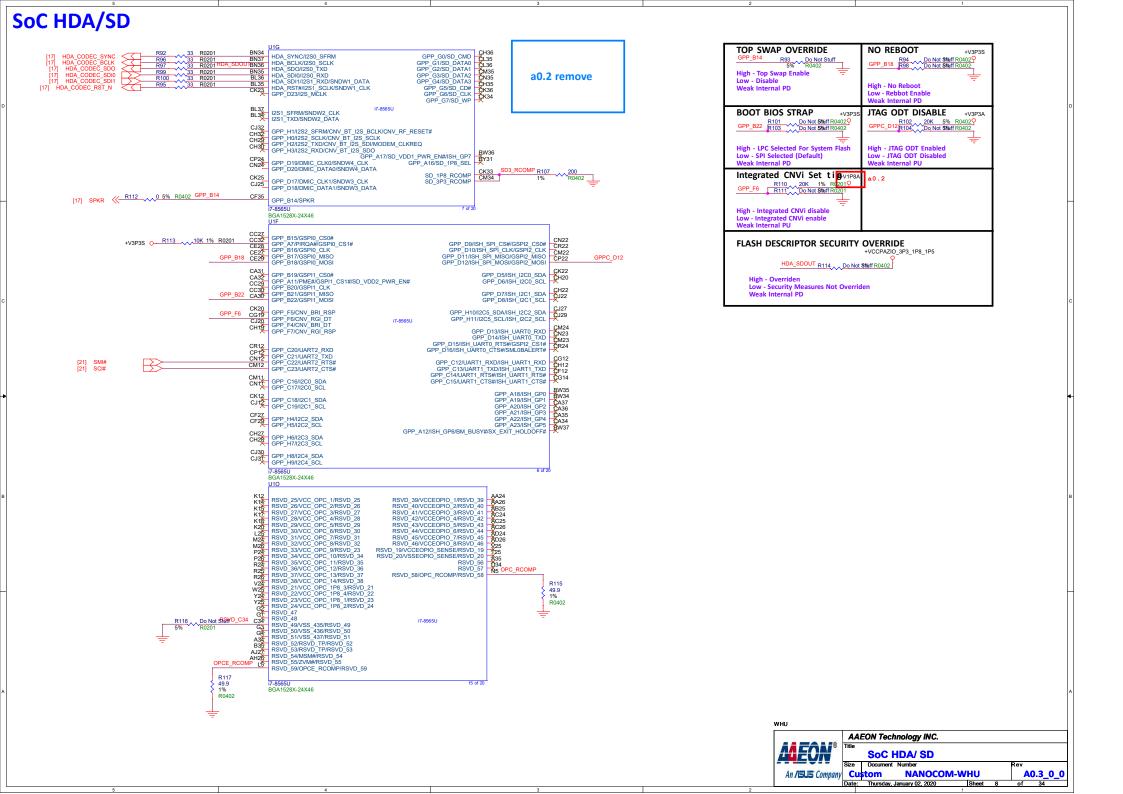


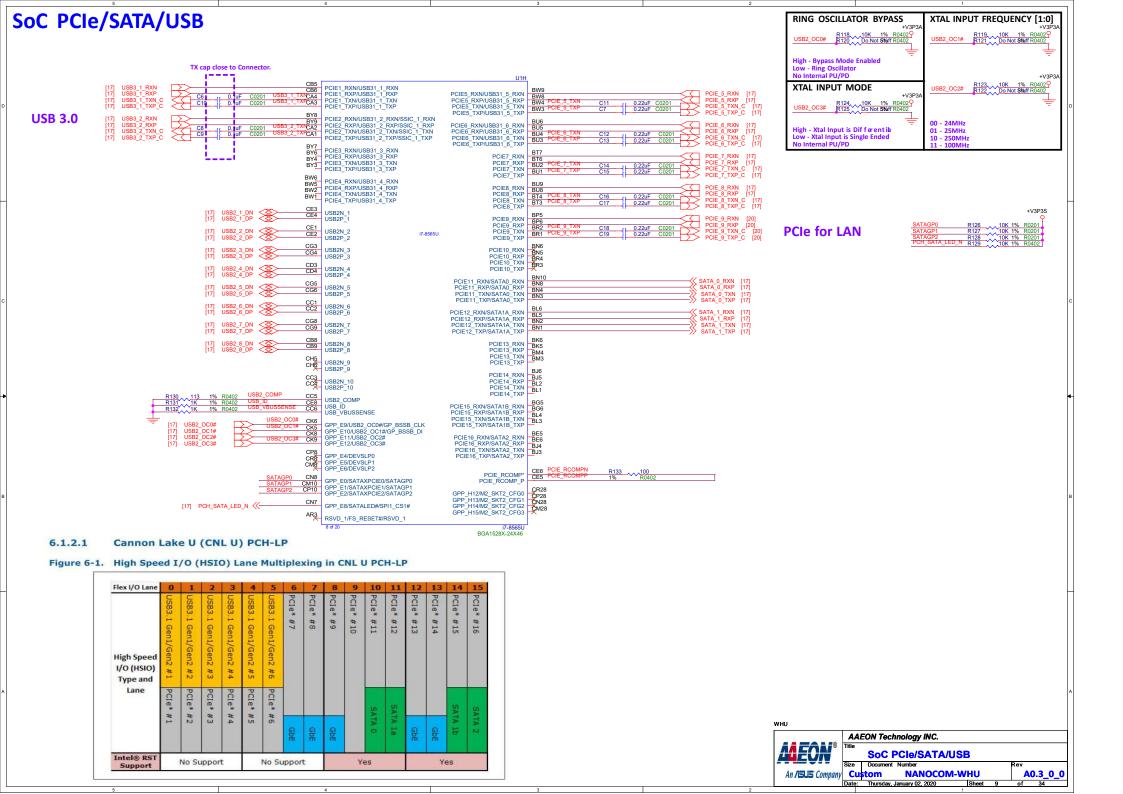


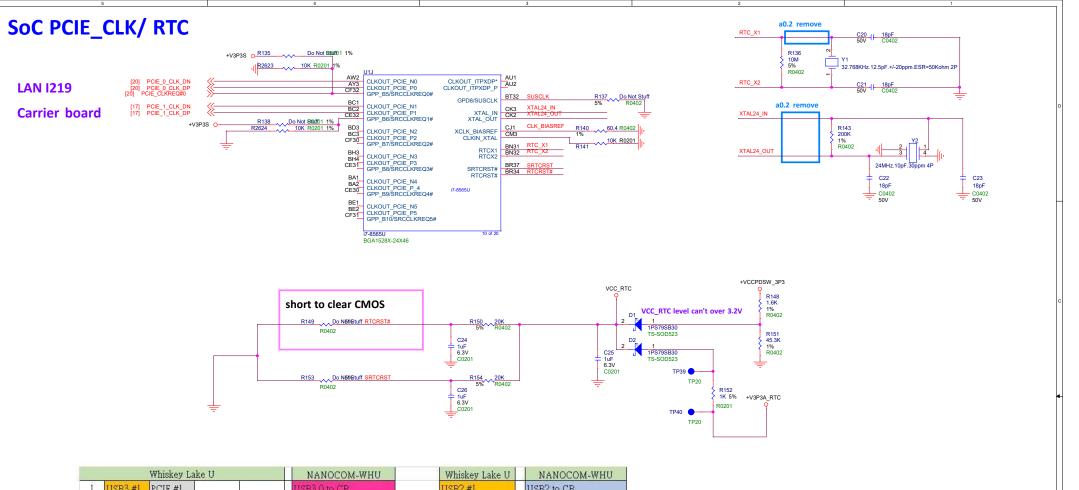






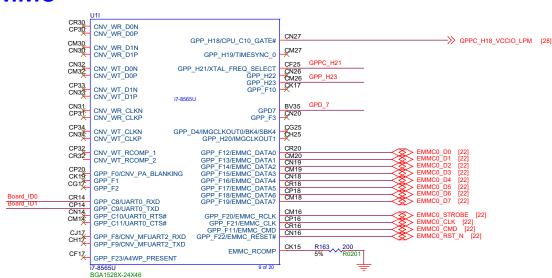




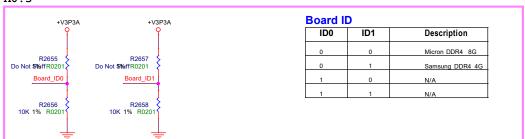


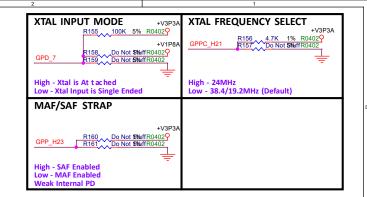
	7	Whiskey L	ake U		NANOCOM-WHU	Whiskey Lake U	NANOCOM-WHU
1	USB3 #1	PCIE #1			USB3.0 to CB	USB2 #1	USB2 to CB
2	USB3 #2	PCIE #2			USB3.0 to CB	USB2 #2	USB2 to CB
3	USB3 #3	PCIE #3				USB2 #3	USB2 to CB
4	USB3 #4	PCIE #4				USB2 #4	USB2 to CB
5	USB3 #5	PCIE #5			PCIE [X4]	U\$B2 #5	USB2 to CB
6	USB3 #6	PCIE #6			PCIE [X4]	USB2 #6	USB2 to CB
7		PCIE #7	GbE		PCIE [X4]	USB2 #7	USB2 to CB
8		PCIE #8	GbE		PCIE [X4]	USB2 #8	USB2 to CB
9		PCIE #9	GbE		PCIE for LAN i219	USB2 #9	
10		PCIE #10		Intel RST		USB2 #10	
11		PCIE #11	SATA 0	Support			
12		PCIE #12	SATA 1A				
13		PCIE #13	GbE				
14		PCIE #14	GbE	Intel RST			
15		PCIE #15	SATA 1b	Support			
16		PCIE #16	SATA 2		0 0		

### **SoC eMMC**



#### A0.3





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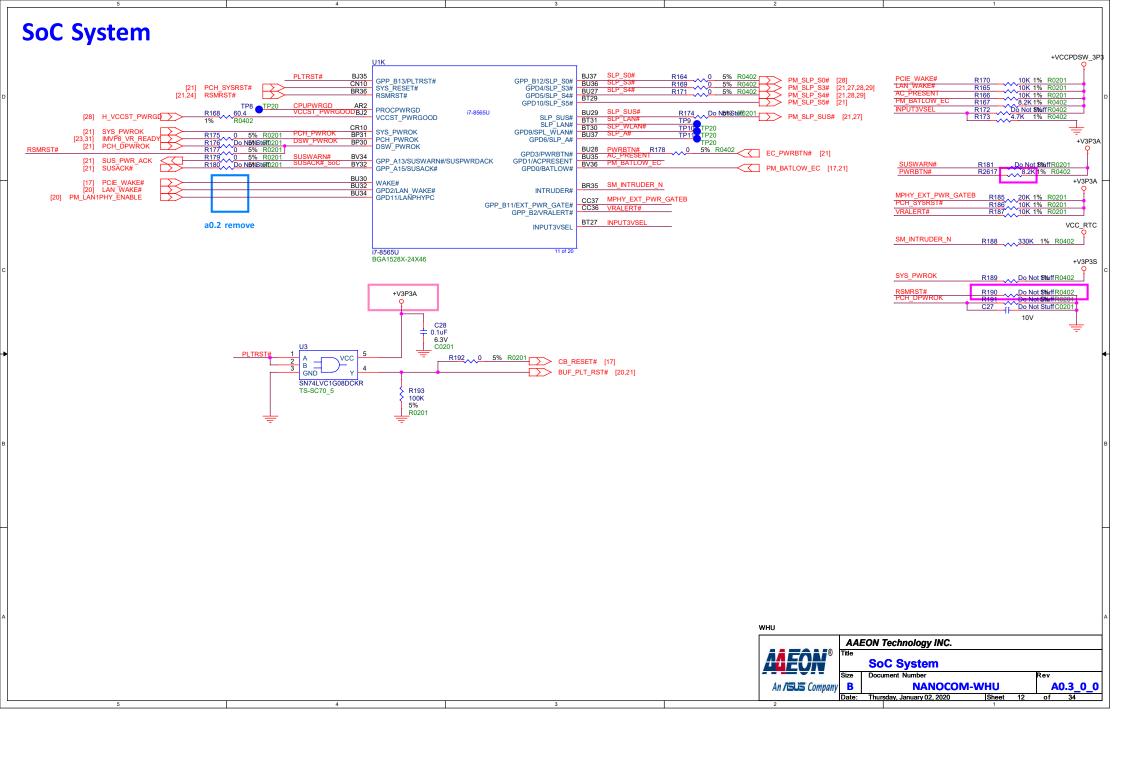
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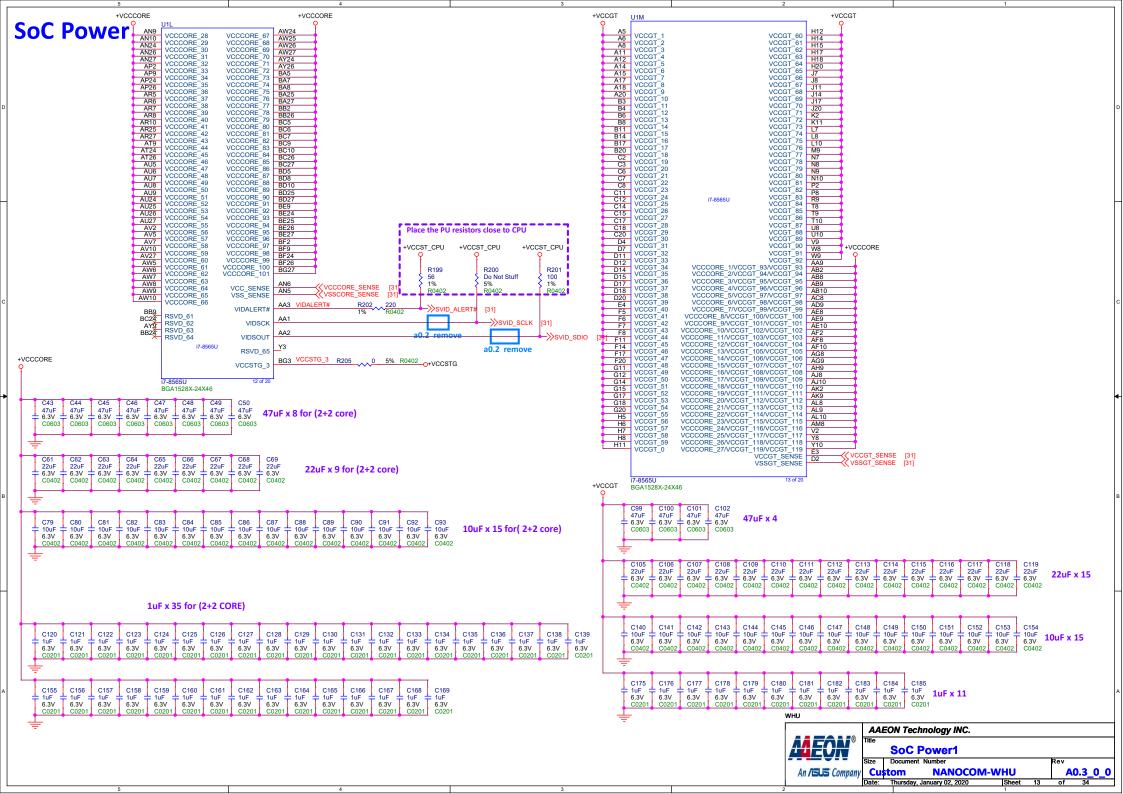
SoC eMMC

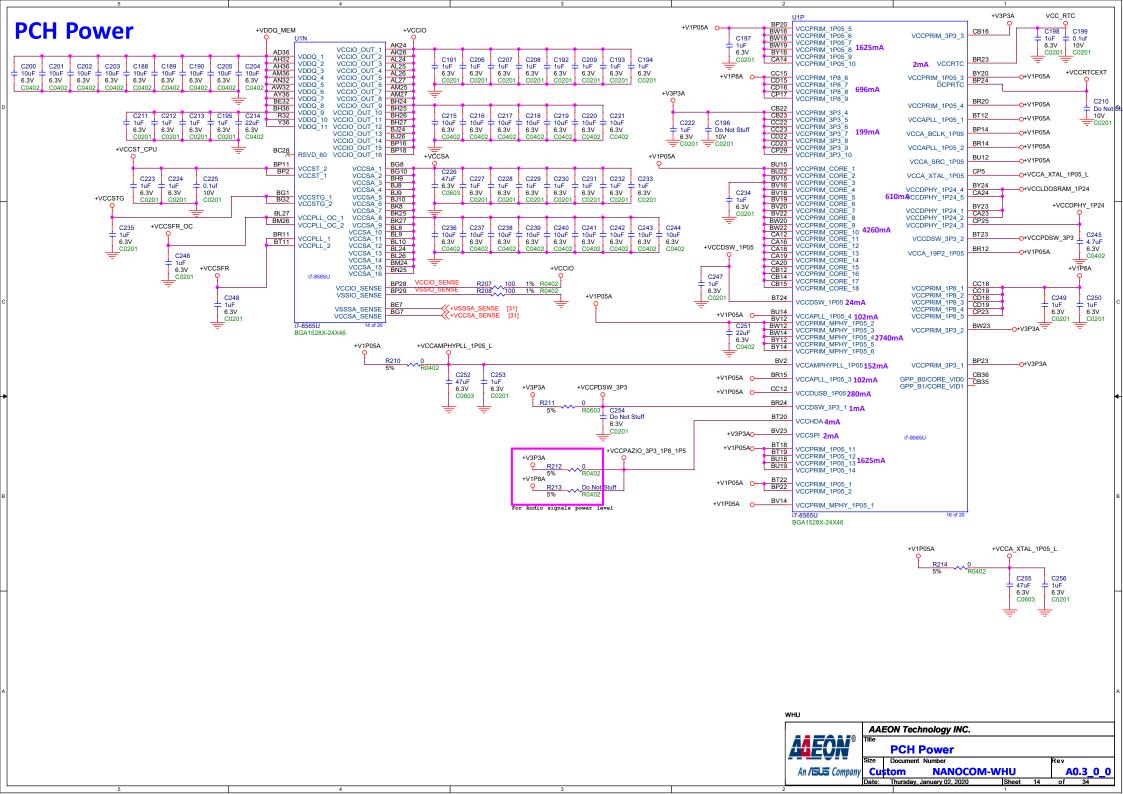
Size | Document Number

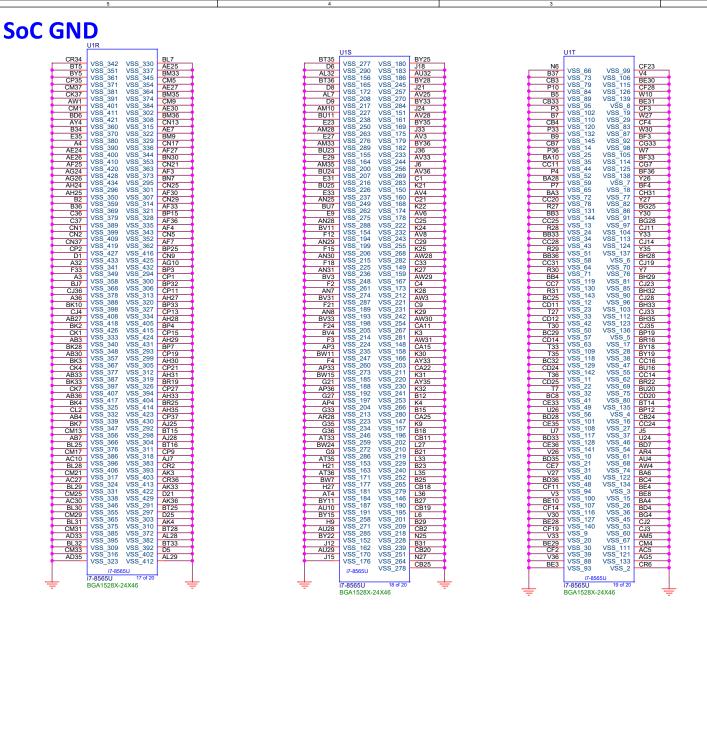
Custom | NANOCOM-WHU | A0.3\_0\_0

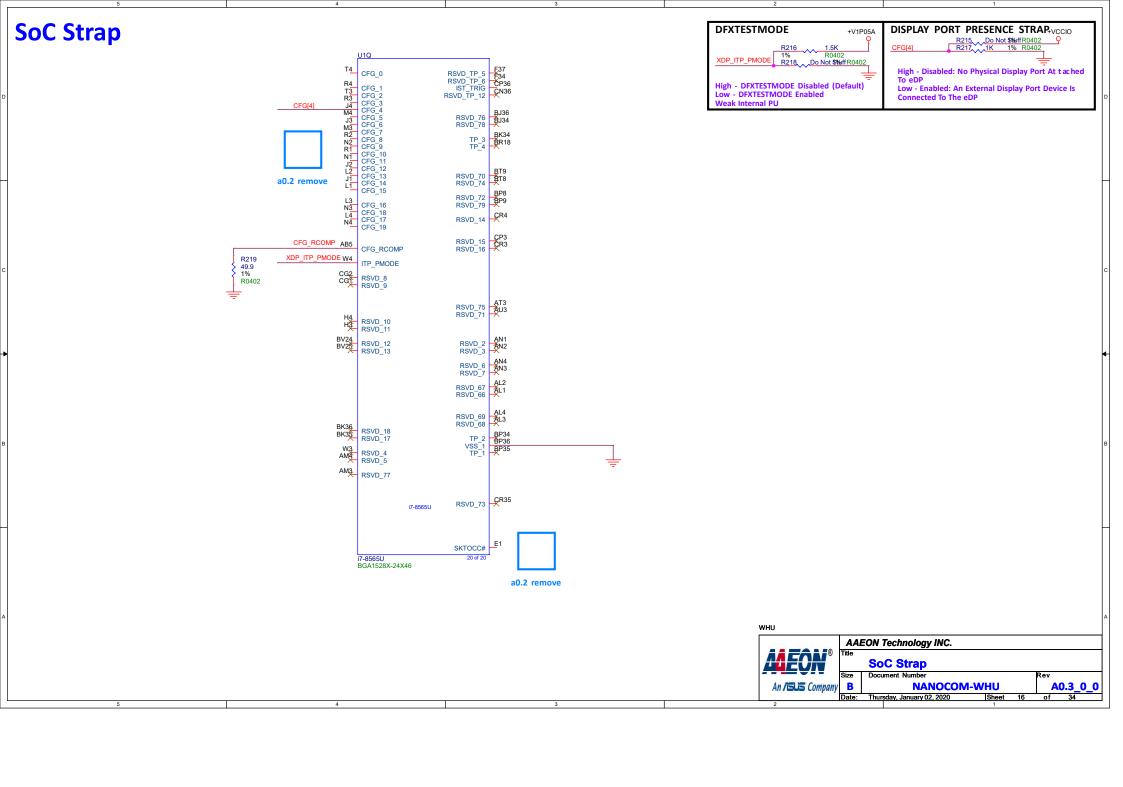
Date: Thursday, January 02, 2020 | Sheet | 11 | of | 34

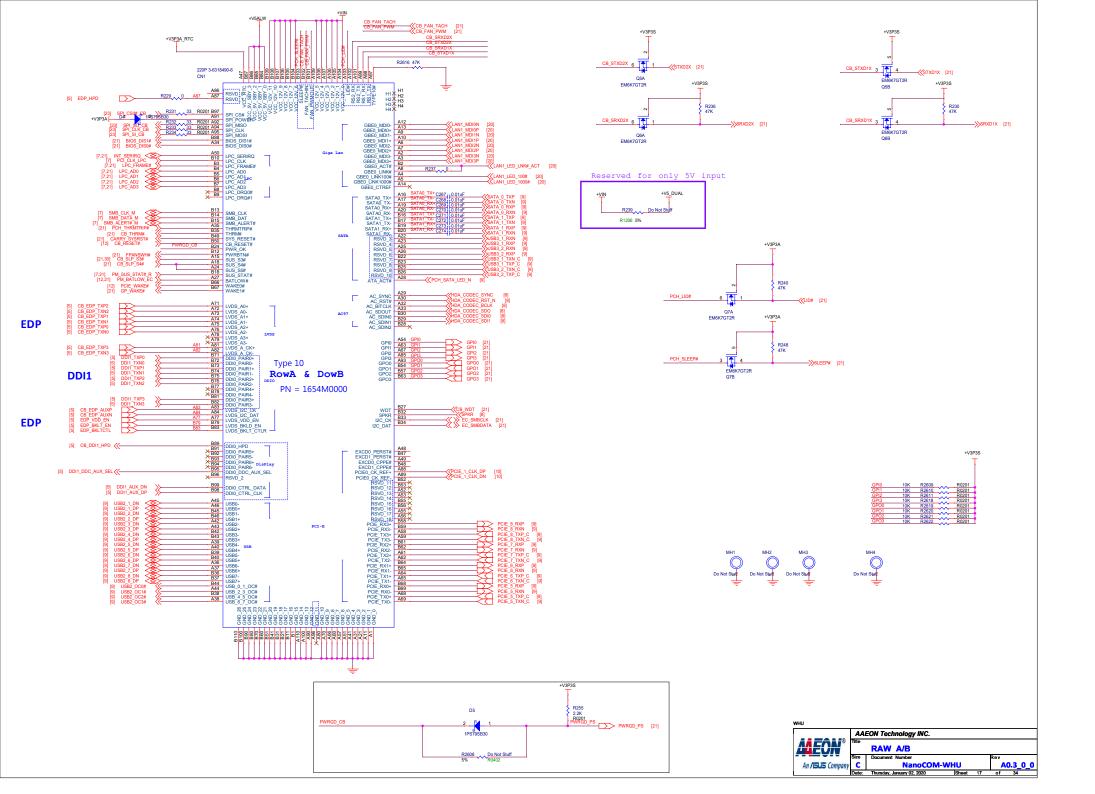


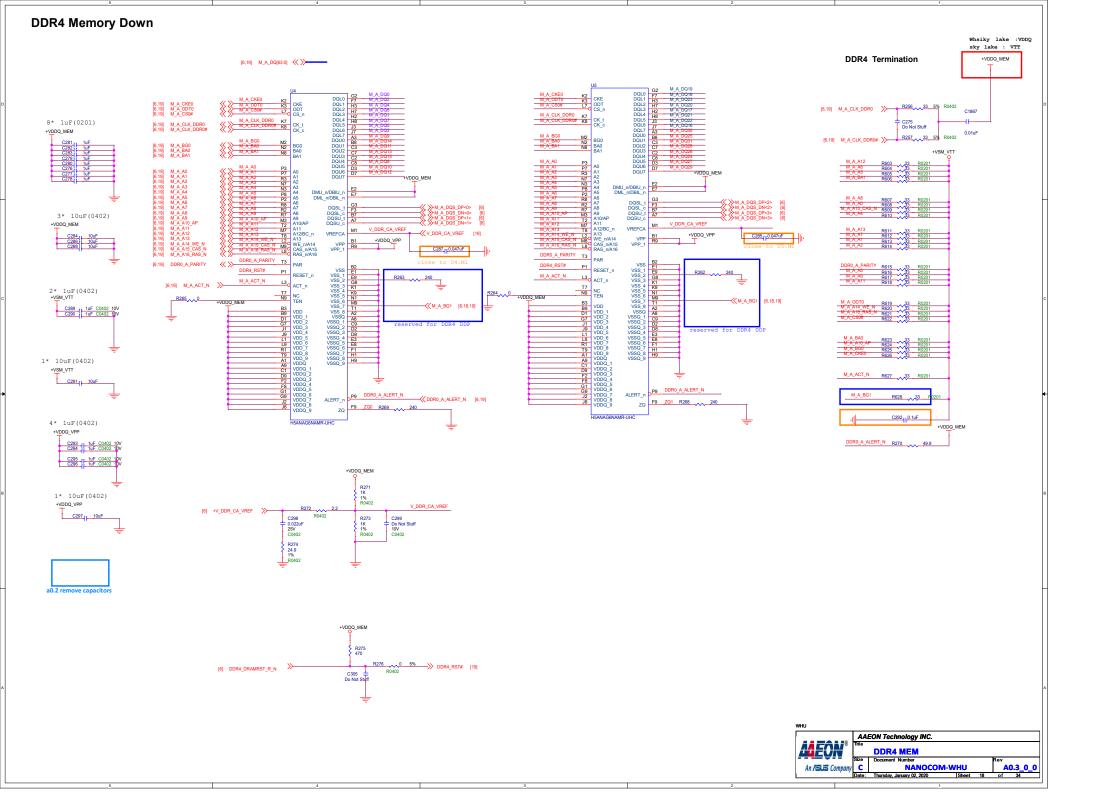


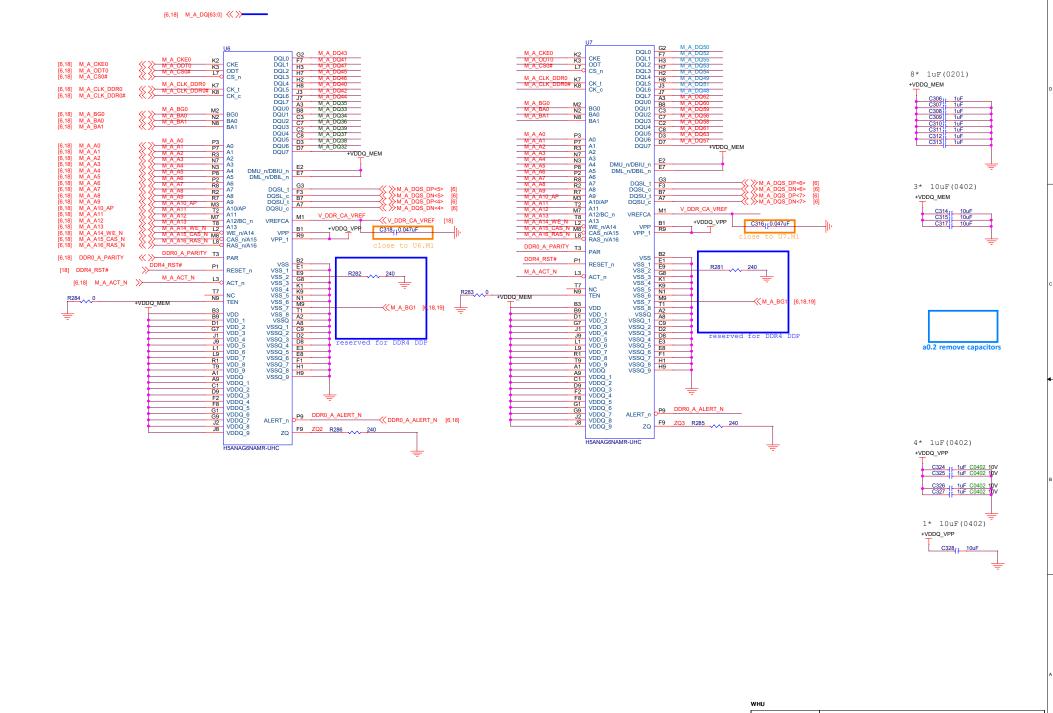




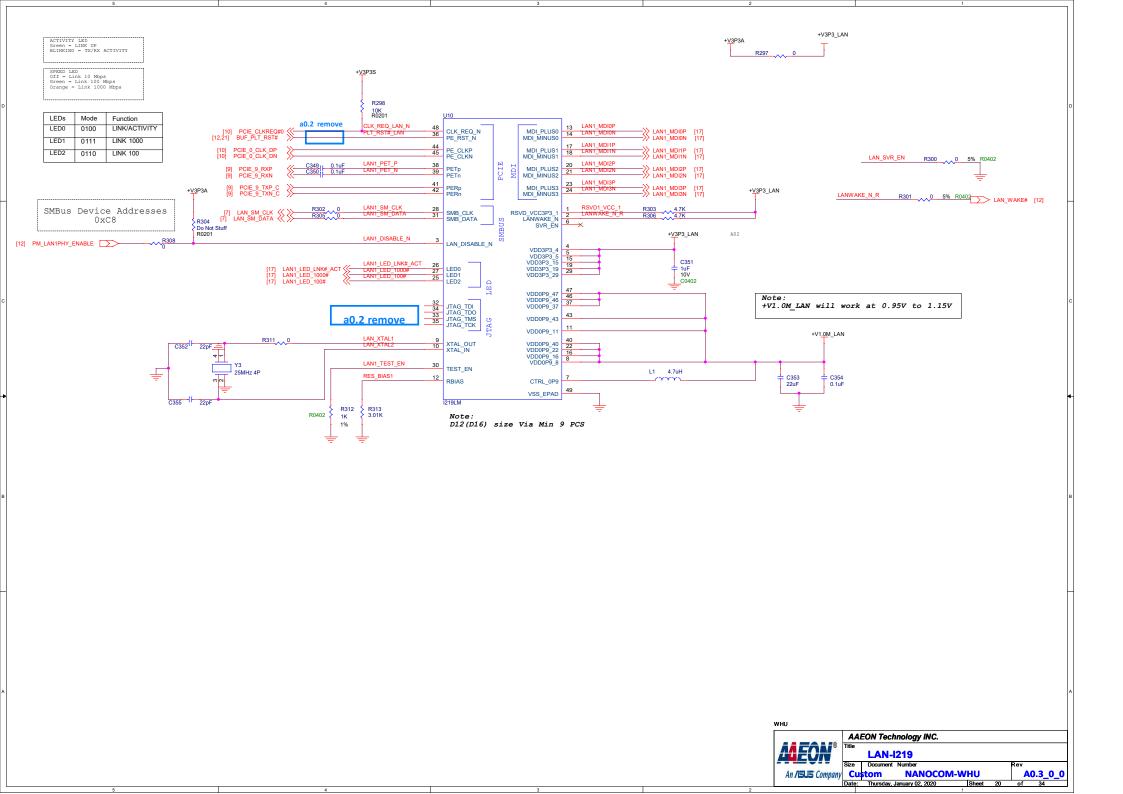




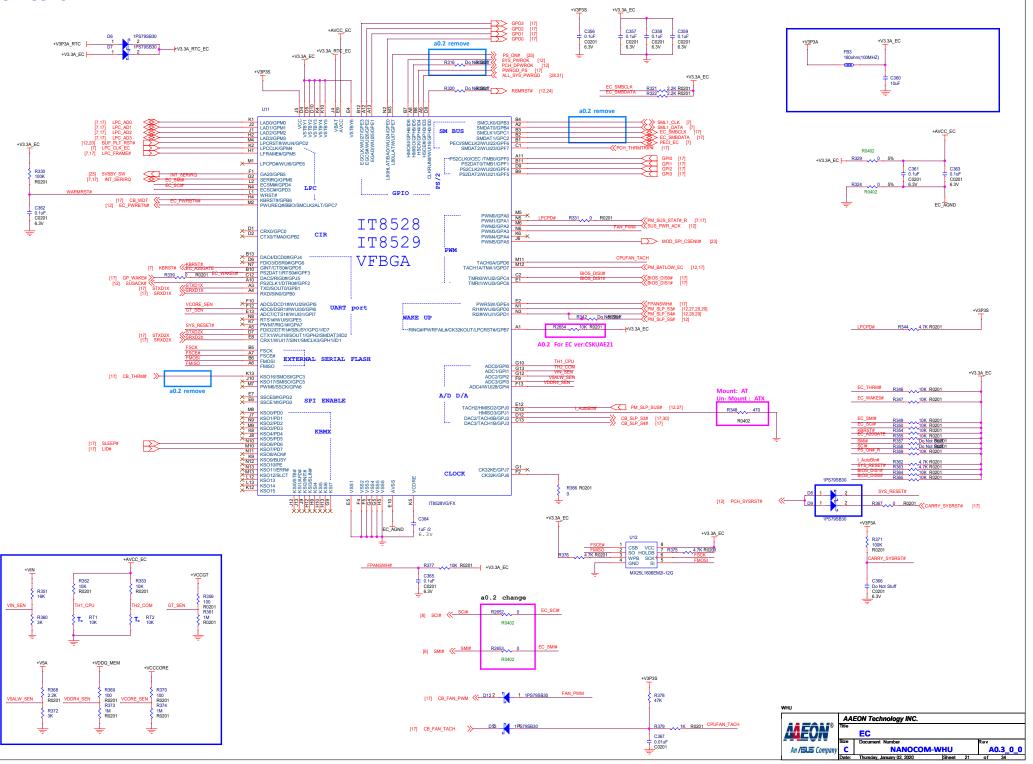


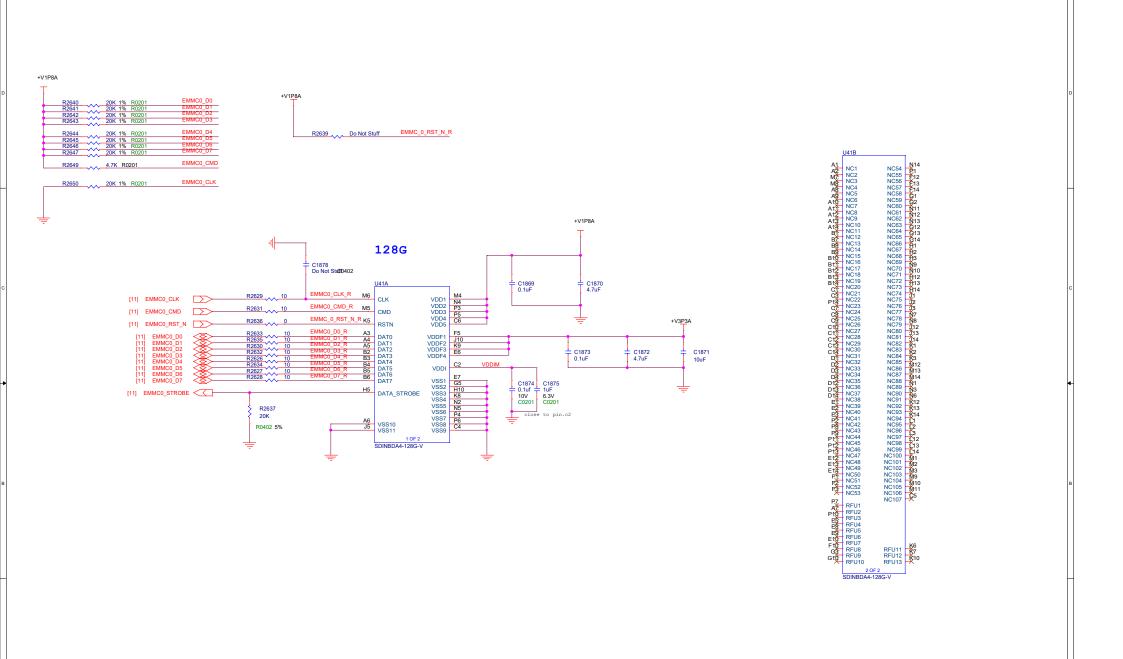


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Tatle DDR4 MEM
Size Document Number Rev
Custom NANOCOM-WHU A0.3\_0\_0
Date: Thursday, January 02, 2020 Sheet 19 of 34

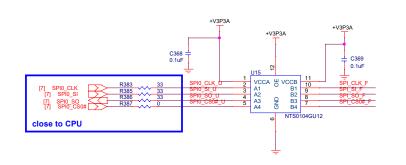


### **EC IT8528**

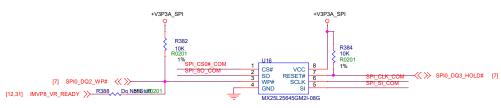




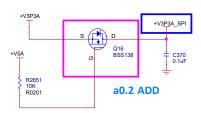
Title EMMC
Size Custom NANOCOM-WHU Rev: A0.3\_0\_0
Date: Thursday, January 02, 2020 Sheet: 22 of 34

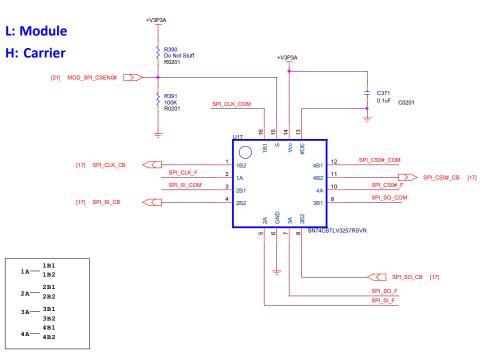


## **BIOS**



1462002564 (TF)IC.Flash Memory.256M Bit serial.SOP-8(209mil).w/ Dual & Quad SPI.SMD.MACRONIX.MX25L25645GM2I-08G A0.2 Change to 32M

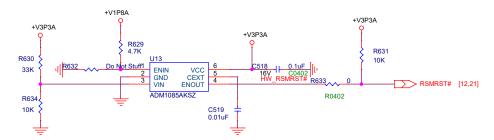




- 1	IIVE	113	FUNCTION		
	ŌĒ	S			
ı	L	L	A port = B1 port		
	L	H	A port = B2 port		
	Н	X	Disconnect		

WHU	AAEON Technology INC.	
<b>MEON®</b>	FAN/BIOS/ LPC/ HW Monitor	
	Size Document Number	Rev
An /ISUS Company	Custom NANOCOM-WHU	A0.3_0_0
	Date: Thursday, January 02, 2020 Sheet 23	of 34

## **RSMRST# Control**



 $3.3V \times 10 / (10+33) = 0.767$ 

ENIN VIH = 0.3\*VCC+0.2 =1.19V ENIN VIL = 0.3\*VCC- 0.2 = 0.79V

ENOUT/ENOUT# Voltage Low (MAX =0.4V),When
Vin < Vth\_falling (ENOUT) / Vin >
Vth\_rising (ENOUT#)

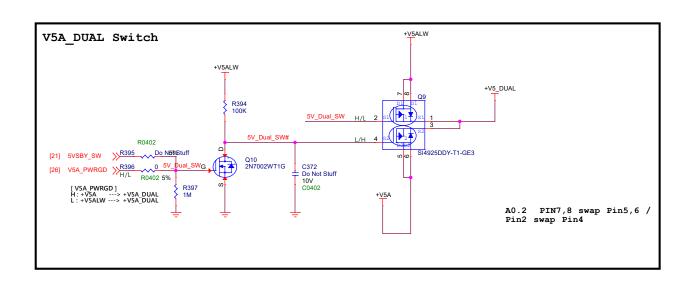
Table 2.

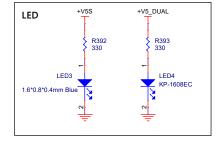
Parameter	Min	Тур	Max	Unit	Test Conditions/Comments
SUPPLY	-		- 10 September 1		
Vcc Operating Voltage Range	2.25		3.6	V	
V <sub>IN</sub> Operating Voltage Range	0		22	V	
Supply Current		10	15	μА	
VIN Rising Threshold, VTH_RISING	0.56	0.6	0.64	V	V <sub>CC</sub> = 3.3 V
VIN Falling Threshold, VTH_FALLING	0.545	0.585	0.625	V	V <sub>CC</sub> = 3.3 V
V <sub>IN</sub> Hysteresis		15		mV	

WHU



	AA	AEON Technology INC.							
R)	Title								
	RSMEST# Control								
	Size	Document Number			Rev				
iny	В	NANOCOM	1-WHU		A	0.3_0	_0		
	Date:	Thursday, January 02, 2020	Sheet	24	of	34			





Discharge Circuit

+V3P3S

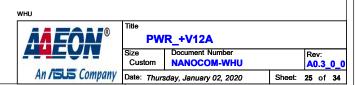
+V5S

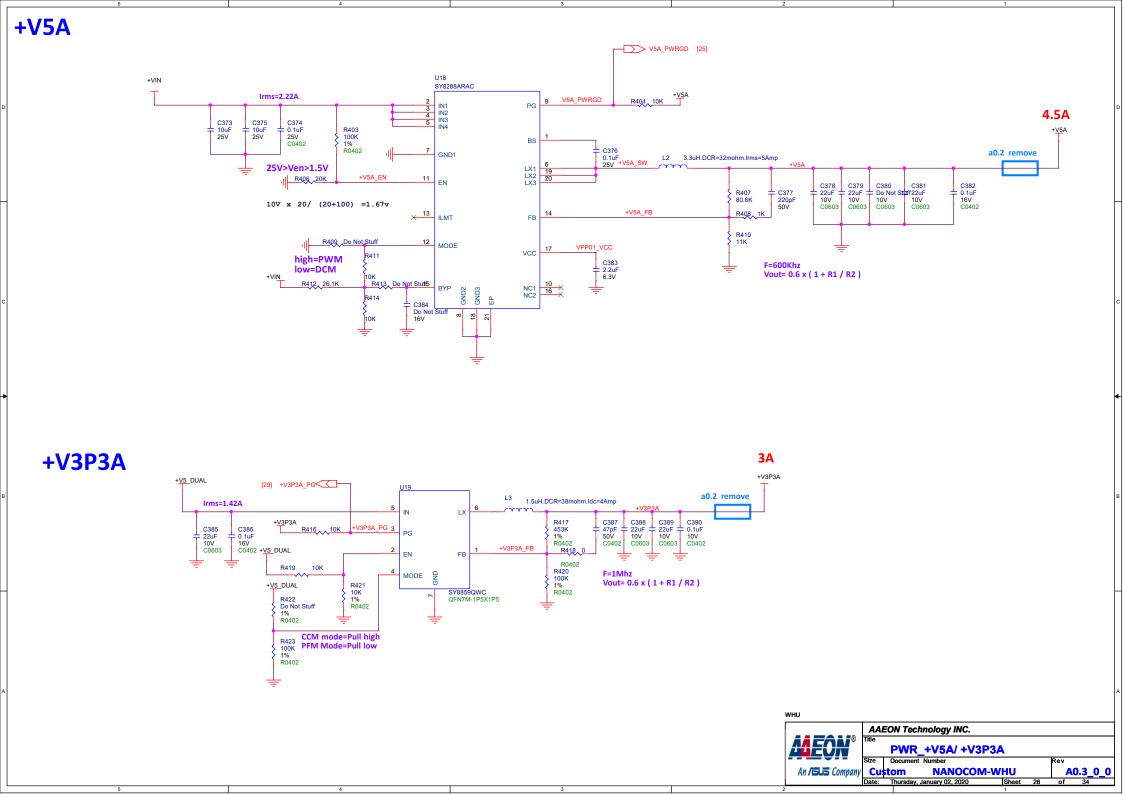
+V5S

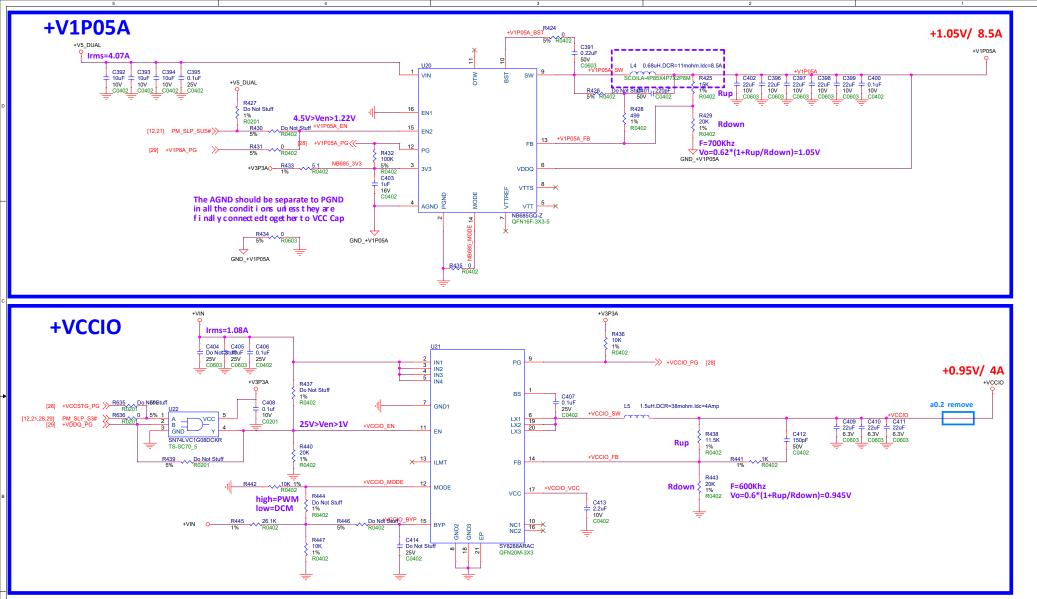
+VCCSTG

R398
20
1%
R0603

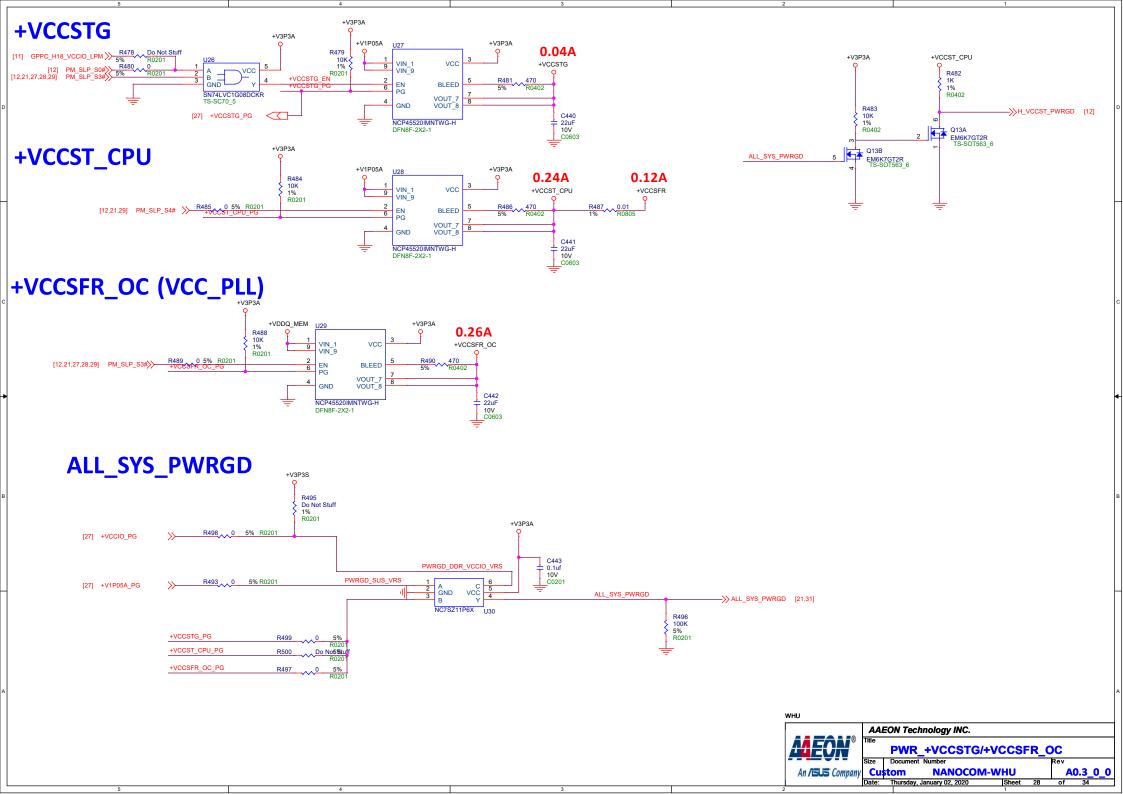
1%
R0603

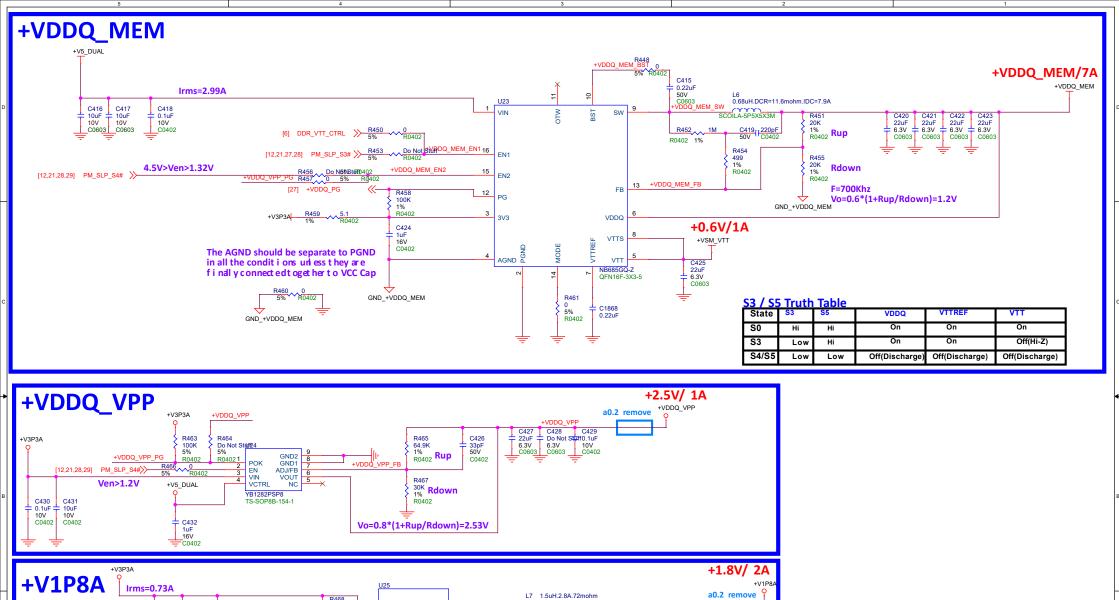


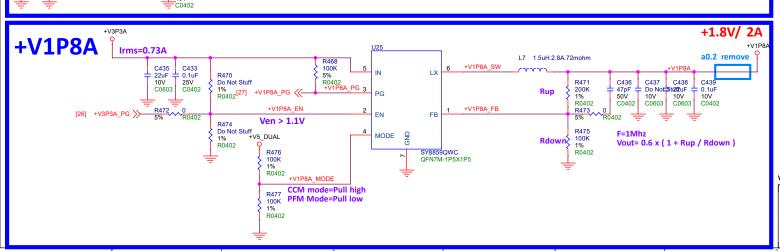


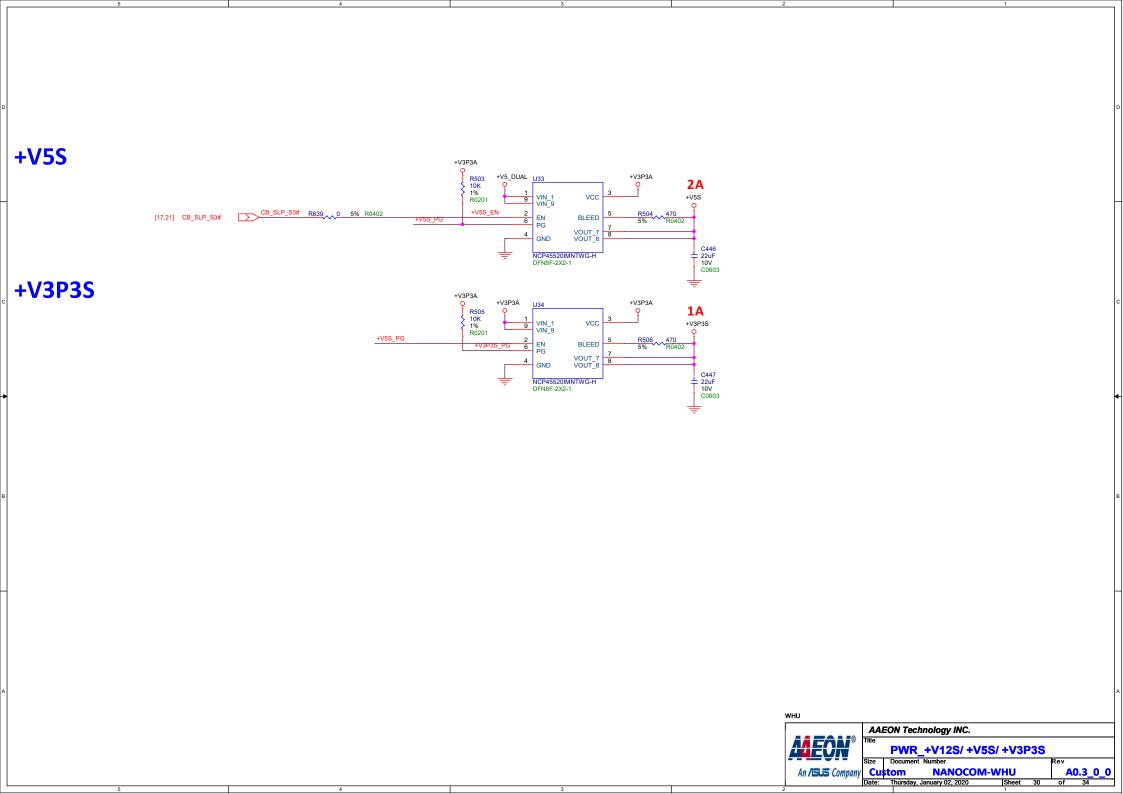


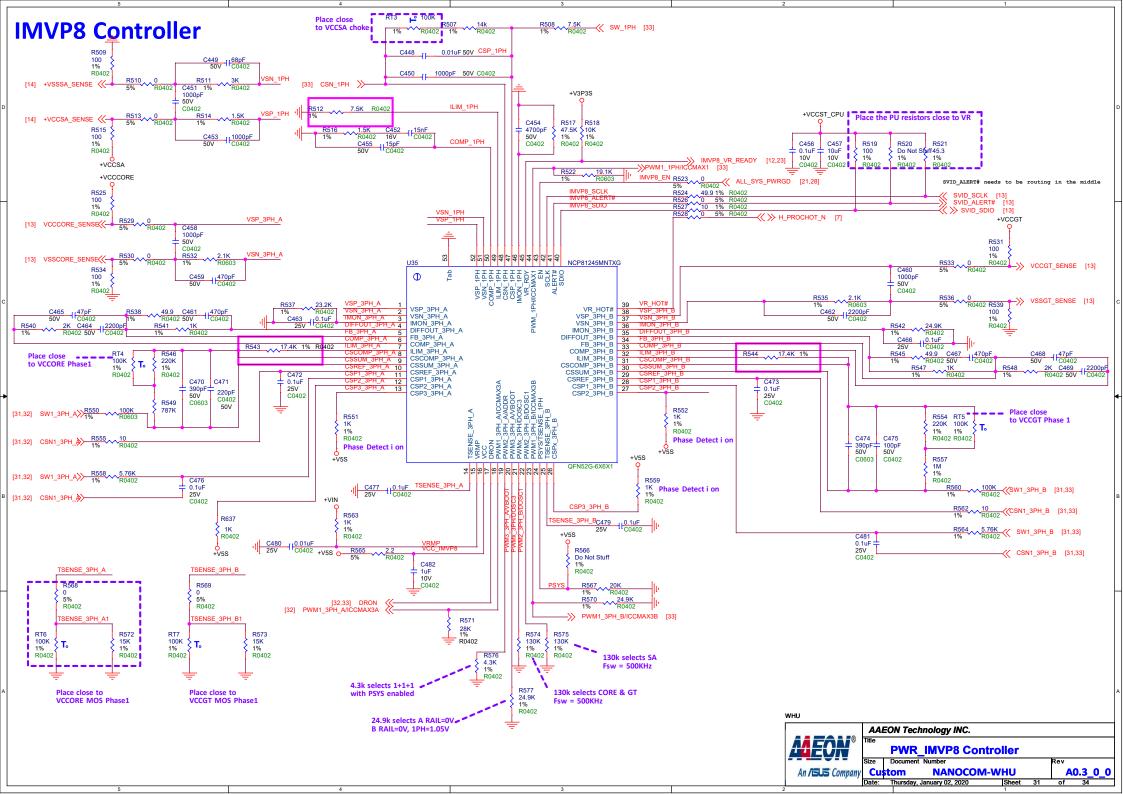
\*Spec: It is strongly recommended that the SLP\_S3# be a qualifying input signal to ALL\_SYS\_PWRGD logic, which drives IMVP VR ON inputs. Additionally, it is recommended that SLP\_S3# also qualify the EN control to the VCCIO power supply

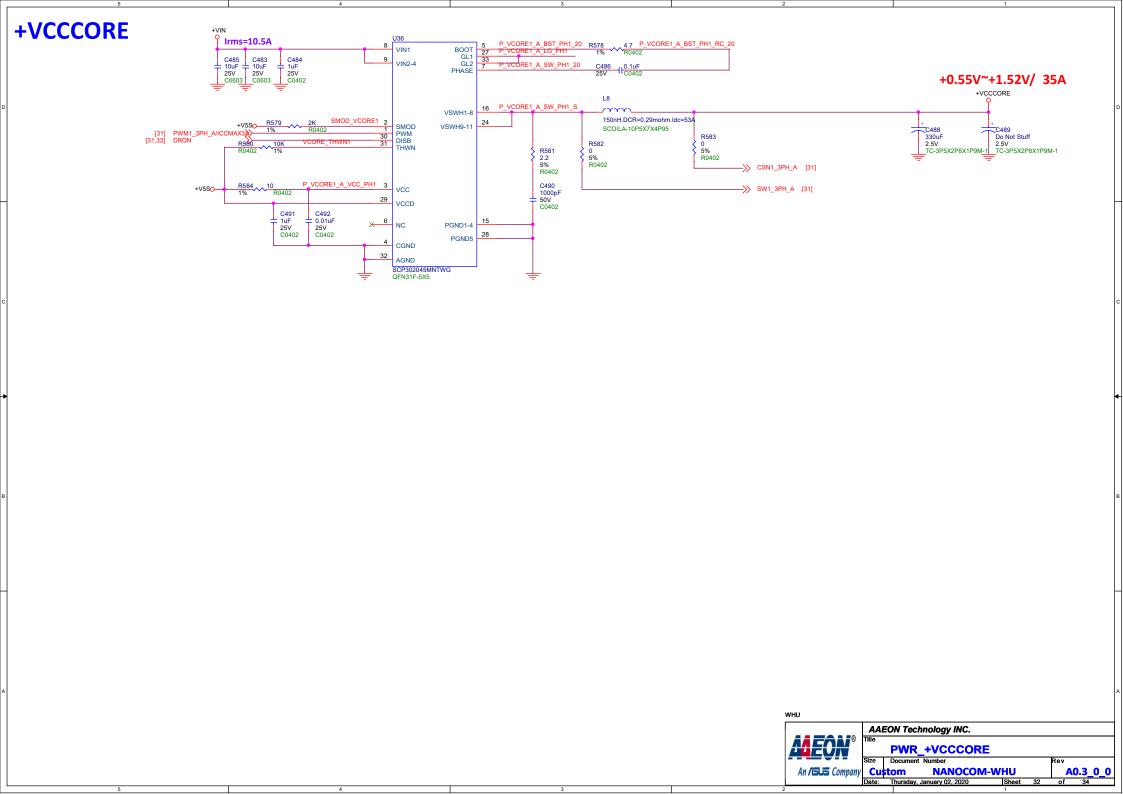


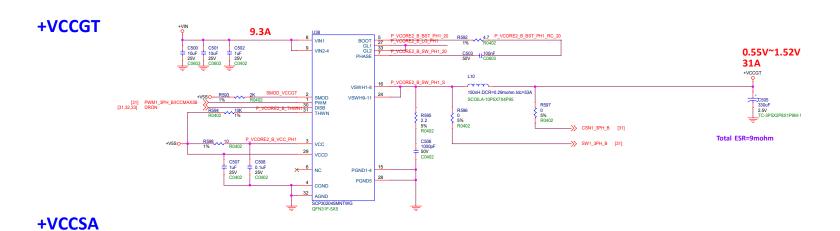


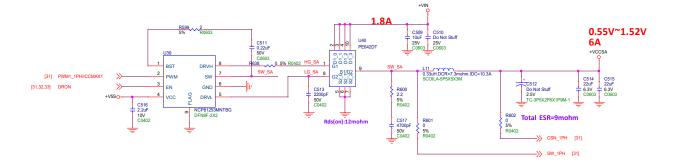












### **HISTORY**

Date	Revision	Page	Modification list	Reason
2019/4/XX	A0.1_0_0	1-32	First Release	First Release
2019/6/18	A0.2_0_0	25-32	Unmount C437 for cost down. Unmount R422 for Frequency adjust. Unmount C380 for cost down. Unmount C404 for cost down. Unmount R444 for Frequency adjust.Mount R442 for Frequency adjust. Monut C500 for Vin adjust Change R544 from 12kohm to 17.4kohm(1050517424) for OCP adjust. Monut C483 for Vin adjust. Unmount C489 for cost down. Change R543 from 10kohm to 17.4kohm(1050517424) for OCP adjust. Change R543 from 16kohm to 7.5kohm(1050507524) for OCP adjust. ADD R2617 8.2K for PWRBTN# sequence	For power test and request
2019/7/23	A0.2_0_0		Mount R212, un-mount R213	
2019/8/6 2019/9/24			Change DIO signal to EC from chipset ADD EMMC U41 schematice  ADD R2654 For EC ver:CSKUAE21  SCI#,SMI# remove diode and change to 0 ohm(R2652,R2653)  Add Q16 for BIOS	
2019/12/25	A0.3_0_0		Add Board ID circuit	